

## NPN complex transistor with switching diode

Parameter	Value
V <sub>CEO</sub>	50V
IC	150mA

# SOT-353 SC-88A

UMT5

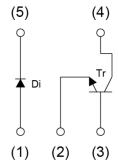
### Features

1)The 2SC4617 and a diode are housed independently in a SOT-353 package.

#### •Inner circuit

Outline

- (1) Di Anode(2) Tr Emitter
- (3) Tr Base(4) Tr Collector
- (5) Di Cathode



## Application

Low-frequency

## Packaging specifications

Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
UML2N	SOT-353 (UMT5)	2021	TR	180	8	3000	L2

# ● Absolute maximum ratings (T<sub>a</sub> = 25°C)

## Pin No.1-5 Diode

Parameter	Symbol	Value	Unit
Reverse voltage	V <sub>R</sub>	80	V
Repetitive peak reverse voltage	V <sub>RM</sub>	80	V
Average rectified current	I <sub>F</sub>	100	mA
Peak forward current	I <sub>FM</sub>	300	mA
Surge current	I <sub>surge</sub>	4	А
Rated in slash put frequency	f	100	MHz

## Pin No.2-3-4 Transistor

Parameter	Symbol	Value	Unit
Collector-base voltage	$V_{CBO}$	60	V
Collector-emitter voltage	$V_{CEO}$	50	V
Emitter-base voltage	$V_{EBO}$	6	V
Collector current	I <sub>C</sub>	150	mA

### **Each element**

Parameter	Symbol	Value	Unit
Power dissipation	P <sub>D</sub> *1,*2	150	mW/Total
Junction temperature	T <sub>j</sub>	150	°C
Range of storage temperature	T <sub>stg</sub>	-55 <b>~</b> +150	°C

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

#### Pin No.1-5 Diode

Darameter	Cymahal			Values	Values	
Parameter	Symbol Conditions -		Min.	Тур.	Max.	Unit
Forward voltage	$V_{F}$	I <sub>F</sub> = 100mA	-	-	1.2	V
Reverse current	$I_R$	V <sub>R</sub> = 70V	-	-	100	nA
Capacitance between terminals	$C_{T}$	V <sub>R</sub> = 6V , f = 1MHz	-	-	3.5	pF
Reverse recovery time	t <sub>rr</sub>	$V_R = 6V$ , $I_F = 5mA$ $R_L = 50\Omega$ (Figure 1)	-	-	4	ns

### Pin No.2-3-4 Transistor

Downwater	Cymala al	Conditions	Values			Lloit
Parameter	Symbol	Symbol Conditions -		Тур.	Max.	Unit
Collector-base breakdown voltage	BV <sub>CBO</sub>	I <sub>C</sub> = 50μA	60	-	1	V
Collector-emitter breakdown voltage	BV <sub>CEO</sub>	I <sub>C</sub> = 1mA	50	-	1	V
Emitter-base breakdown voltage	BV <sub>EBO</sub>	I <sub>E</sub> = 50μA	6	-	1	V
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> = 60V	-	-	100	nA
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> = 5V	1	-	100	nA
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> = 50mA, I <sub>B</sub> = 5mA	1	-	400	mV
DC current gain	h <sub>FE</sub>	$V_{CE} = 6V, I_C = 1mA$	120	-	560	-
Transition frequency	f <sub>T</sub> *3	V <sub>CE</sub> = 12V, I <sub>E</sub> = -2mA, f = 100MHz	-	180	-	MHz
Output capacitance	C <sub>ob</sub>	V <sub>CB</sub> = -12V, I <sub>E</sub> = 0A, f = 1MHz	-	2.0	3.5	pF

<sup>\*1</sup> Each termunal mounted on a reference land.

<sup>\*2 120</sup>mW per element must not be exceeded.

<sup>\*3</sup> Characteristics of built-in transistor.

## ● Electrical characteristic curves(Ta=25°C) < For Diode>

Fig.1 Reverse Current vs.
Reverse Voltage

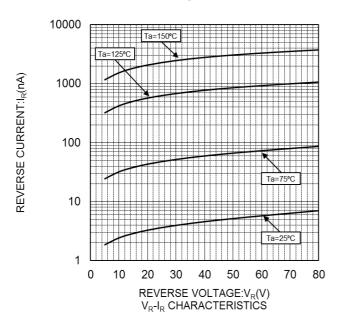


Fig.2 Forward Current vs. Forward Voltage

FORWARD CURRENT: I<sub>F</sub>(mA)

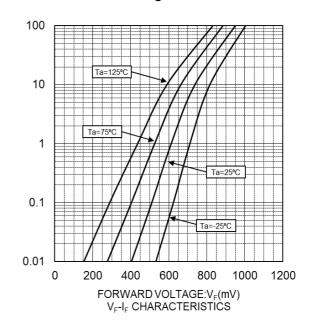
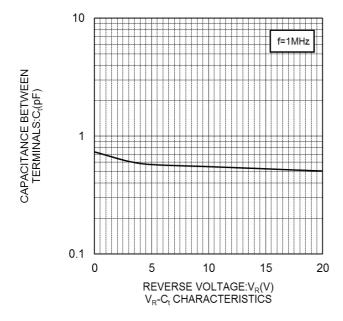
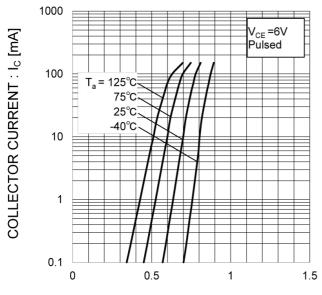


Fig.3 Capacitance Between Terminals vs. Reverse Voltage



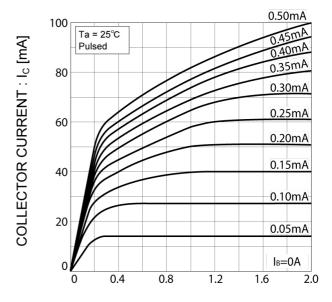
## ● Electrical characteristic curves(Ta=25°C) < For Transistor>

Fig.4 Ground Emitter Propagation Characteristics



BASE TO EMITTER VOLTAGE :  $V_{BE}\left[V\right]$ 

Fig.5 Typical Output Characteristics



COLLECTOR TO EMITTER VOLTAGE: V<sub>CE</sub> [V]

Fig.6 DC Current Gain vs. Collector Current (I)

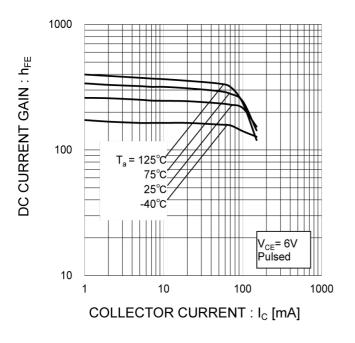
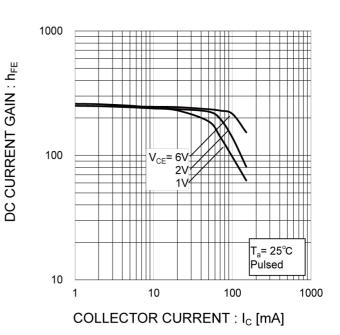


Fig.7 DC Current Gain vs. Collector Current (II)



## ● Electrical characteristic curves(T<sub>a</sub>=25°C) < For Transistor>

Fig.8 Collector-Emitter Saturation Voltage vs. Collector Current (I)

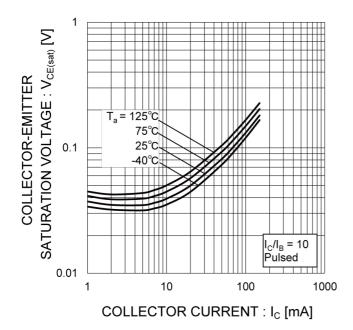


Fig.9 Collector-Emitter Saturation
Voltage vs. Collector Current (II)

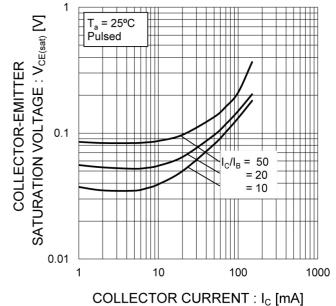


Fig.10 Base-Emitter Saturation Voltage vs. Collector Current

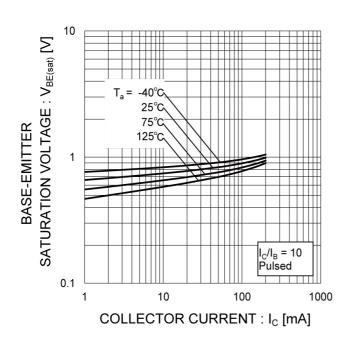
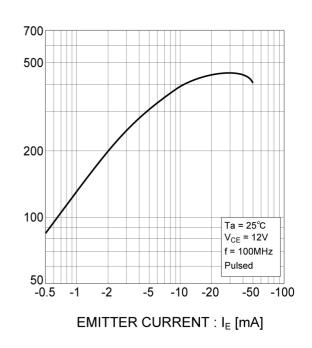


Fig.11 Gain Bandwidth Product vs. Emitter Current

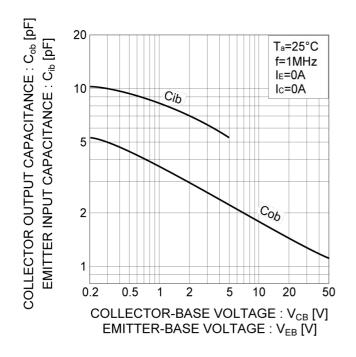


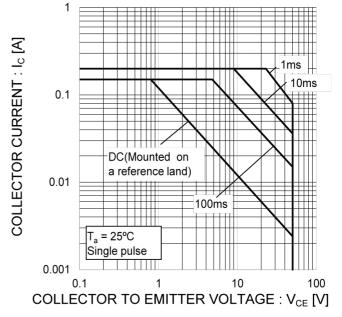
TRANSITION FREQUENCY: fr [MHz]

## ● Electrical characteristic curves(T<sub>a</sub>=25°C) < For Transistor>

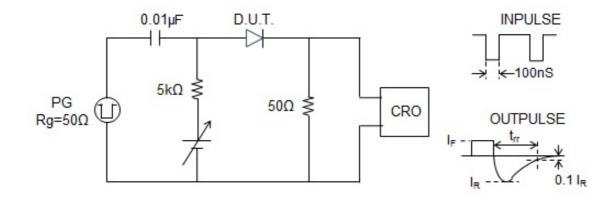
Fig.12 Emitter Input Capacitance vs.
Emitter-Base Voltage
Collector Output Capacitance vs.
Collector-Base Voltage

Fig.13 Safe Operating Area

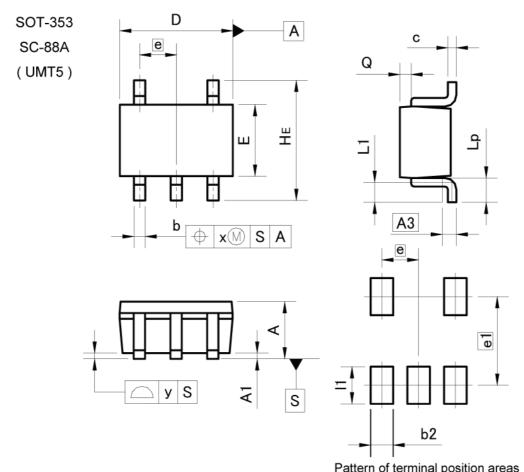




(figure 1) Reverse recovery time test circuit



## Dimensions



Pattern of terminal position areas
[Not a pattern of soldering pads]

MILIMETERS
INCHES

DIM	MILIMETERS		INC	HE2
DIW	MIN	MAX	MIN	MAX
Α	0.80	1.00	0.031	0.039
A1	0.00	0.10	0.000	0.004
A3	0.5	25	0.0	10
b	0.15	0.30	0.006	0.012
С	0.10	0.20	0.004	0.008
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
е	0.	0.65		26
HE	2.00	2.20	0.079	0.087
L1	0.10	0.40	0.004	0.016
Lp	0.25	0.55	0.010	0.022
Q	0.10	0.30	0.004	0.012
х	<del></del>	0.10		0.004
У	<del></del> 0	0.10	0.50	0.004

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b2	=	0.40		0.016
e1	1.55		0.0	061
11	-	0.65	-	0.026

Dimension in mm/inches



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JAPAN	USA	EU	CHINA
CLASSⅢ	CI ΛCCπ	CLASS II b	CI VCCIII
CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

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  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
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- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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# UML2N - Web Page

**Distribution Inventory** 

Part Number	UML2N
Package	UMT5
Unit Quantity	3000
Minimum Package Quantity	3000
Packing Type	Taping
Constitution Materials List	inquiry
RoHS	Yes